

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L3	585740	(flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:21
2	BRS	L4	321047 8	(diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:21
3	BRS	L5	58762	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:22

	Type	L #	Hits	Search Text	DBs	Time Stamp
4	BRS	L6	1648	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)) and ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:22
5	BRS	L7	320781 2	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:23
6	BRS	L8	109486	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4 or support\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:23

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L9	795234	interconnect\$6 or inter-connect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:23
8	BRS	L10	243663 2	reaction or react\$6 or polymerization	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:23
9	BRS	L11	205285 5	substrate or wafer	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:23
10	BRS	L12	28272	polymer\$4 near2 (foam\$6 or bubbles or spray\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:24
11	BRS	L13	50933	(expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:24

	Type	L #	Hits	Search Text	DBs	Time Stamp
12	BRS	L14	22312	polymer\$4 near2 foam\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:24
13	BRS	L15	502	(polymer\$4 near2 foam\$6) near4 (substrates or wafers)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:47
14	BRS	L16	571	(polymer\$4 near2 foam\$6) same interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:24
15	IS&R	L17	492	(438/782).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:24
16	BRS	L18	2380	((438/762).CCLS.) or ((438/765).CCLS.) or ((438/780).CCLS.) or ((438/782).CCLS.)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:24

	Type	L #	Hits	Search Text	DBs	Time Stamp
17	IS&R	L20	1523	(438/780).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:25
18	BRS	L19	158	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)) same ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:27

	Type	L #	Hits	Search Text	DBs	Time Stamp
19	BRS	L21	294	((((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4 or support\$4)) same ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:27
20	BRS	L22	4	((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)) same (reaction or react\$6 or polymerization) same (substrate or wafer)) and (polymer\$4 near2 (foam\$6 or bubbles or spray\$6))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:27
21	BRS	L23	520	((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)) same (reaction or react\$6 or polymerization) same (substrate or wafer)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:28

	Type	L #	Hits	Search Text	DBs	Time Stamp
22	BRS	L24	321	((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)) same (reaction or react\$6 or polymerization) same (substrate or wafer)) and ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:28
23	BRS	L25	286	(polymer\$4 near2 (foam\$6 or bubbles or spray\$6)) and ((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:28
24	BRS	L26	17	((polymer\$4 near2 foam\$6) near4 (substrates or wafers)) same interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:28
25	BRS	L27	18	((polymer\$4 near2 foam\$6) near4 (substrates or wafers)) same (inject\$6 or spray\$6 or diffus\$6 or immers\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:28

	Type	L #	Hits	Search Text	DBs	Time Stamp
26	BRS	L28	233	((polymer\$4 near2 foam\$6) same interconnect\$6) and (substrate or wafer)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:28
27	BRS	L29	7	((438/762).CCLS.) or ((438/765).CCLS.) or ((438/780).CCLS.) or ((438/782).CCLS.)) and (polymer\$4 near2 foam\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:28
28	IS&R	L30	369	(438/762).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:28
29	IS&R	L31	148	(438/765).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:29
30	BRS	L32	72	15 and interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 15:48



	Type	L #	Hits	Search Text	DBs	Time Stamp
31	BRS	L33	72	32 and ((@ad<20030620) or (@rlad<20030620))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 16:15
32	BRS	L34	232	28 and ((@ad<20030620) or (@rlad<20030620))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 16:30
33	BRS	L35	35091	substrates near8 interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 16:29
34	BRS	L36	24037	(second! adj (substrate or wafer)) same (first adj (substrate or wafer))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 16:30
35	BRS	L37	885	36 same interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 16:30

	Type	L #	Hits	Search Text	DBs	Time Stamp
36	BRS	L38	859	37 and ((@ad<20030620) or (@rlad<20030620))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 16:31
37	BRS	L39	302	38 and polymer\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 16:32

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	585740	(flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:42
2	BRS	L2	321047 8	(diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:43
3	BRS	L3	58762	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:44

	Type	L #	Hits	Search Text	DBs	Time Stamp
4	BRS	L4	1648	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)) and ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:44
5	BRS	L5	320781 2	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:45
6	BRS	L6	109486	((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4 or support\$4)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:45

	Type	L #	Hits	Search Text	DBs	Time Stamp
7	BRS	L9	795234	interconnect\$6 or inter-connect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:47
8	BRS	L10	243663 2	reaction or react\$6 or polymerization	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:48
9	BRS	L11	205285 5	substrate or wafer	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:48
10	BRS	L15	28272	polymer\$4 near2 (foam\$6 or bubbles or spray\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:50
11	BRS	L16	50933	(expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:50

	Type	L #	Hits	Search Text	DBs	Time Stamp
12	BRS	L18	22312	polymer\$4 near2 foam\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:51
13	BRS	L19	502	(polymer\$4 near2 foam\$6) near4 (substrates or wafers)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:51
14	BRS	L24	571	(polymer\$4 near2 foam\$6) same interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:52
15	IS&R	L26	492	(438/782).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:52
16	BRS	L27	2380	((438/762).CCLS.) or ((438/765).CCLS.) or ((438/780).CCLS.) or ((438/782).CCLS.)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:52

	Type	L #	Hits	Search Text	DBs	Time Stamp
17	IS&R	L31	1523	(438/780).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:52
18	BRS	L7	158	((((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or "H.sub.20" or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4)) same ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:52

	Type	L #	Hits	Search Text	DBs	Time Stamp
19	BRS	L8	294	((((diisocyanate adj monomers) or (diisocynate adj end-capped adj compliant adj oligomer) or (ptoluenesulfonyl adj semicarbazide) or (hydroxyl adj end-capped adj oligomer) or (carboxylic adj acid adj polymer) or water or (polymer\$6 near2 foam\$6)) near4 (filling or filler or infill or insulat\$4 or support\$4)) same ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:52
20	BRS	L12	4	((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)) same (reaction or react\$6 or polymerization) same (substrate or wafer)) and (polymer\$4 near2 (foam\$6 or bubbles or spray\$6))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:52
21	BRS	L13	520	((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)) same (reaction or react\$6 or polymerization) same (substrate or wafer)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53



	Type	L #	Hits	Search Text	DBs	Time Stamp
22	BRS	L14	321	((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6)) same (reaction or react\$6 or polymerization) same (substrate or wafer)) and ((flip adj chip or BGA or (ball adj grid) or IC or device or package or die or dice or dies) near8 (board or substrate or wafer or PCB or (print adj circuit adj board) or MCM or multi-chip or (multi adj chip) or interposer or leadframe or (lead adj frame)))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53
23	BRS	L17	286	(polymer\$4 near2 (foam\$6 or bubbles or spray\$6)) and ((expose\$4 or top or surface) near4 (interconnect\$6 or inter-connect\$6))	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53
24	BRS	L20	17	((polymer\$4 near2 foam\$6) near4 (substrates or wafers)) same interconnect\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53
25	BRS	L21	18	((polymer\$4 near2 foam\$6) near4 (substrates or wafers)) same (inject\$6 or spray\$6 or diffus\$6 or immers\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53

	Type	L #	Hits	Search Text	DBs	Time Stamp
26	BRS	L25	233	((polymer\$4 near2 foam\$6) same interconnect\$6) and (substrate or wafer)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53
27	BRS	L28	7	((438/762).CCLS.) or ((438/765).CCLS.) or ((438/780).CCLS.) or ((438/782).CCLS.)) and (polymer\$4 near2 foam\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53
28	IS&R	L29	369	(438/762).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53
29	IS&R	L30	148	(438/765).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/28 13:53

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	508	(257/618).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/29 16:43
2	L2	551	(257/620).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/29 16:44
3	L3	1006	(438/107).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/29 16:44
4	L4	2289	(438/612).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/10/29 16:44